

IN THE CLAIMS:

Claims 2 and 14 have been cancelled herein. Claims 7-12 and 19-23 have been withdrawn from consideration. Claims 1 and 13 have been amended herein. All of the pending claims 1 through 23 are presented below. This listing of claims will replace all prior versions and listings in the application. Please enter these claims as amended:

1. (Currently Amended) A resist removal method for use in an automolding system comprising:  
providing an automolding system having a laser;  
providing a substrate having a surface;  
forming resist on at least a portion of the surface; and  
removing at least a portion of [providing a laser to remove] the resist from the substrate using the laser.

2. (Currently Cancelled)

3. (Original) The method according to claim 1 wherein said laser comprises one of an Nd:YAG laser and an excimer laser.

4. (Original) The method according to claim 1 wherein said substrate comprises a ball-grid-array substrate.

5. (Original) The method according to claim 1 further comprising a vision system for detecting resist.

6. (Previously Amended) The method according to claim 5 wherein said vision system comprises:  
providing a laser scanning system; and  
detecting changes in a pattern of the substrate.

7. (Currently Withdrawn) A semiconductor device formed by a laser etching process comprising:

providing a substrate having a surface;

forming resist on at least a portion of the surface; and

etching the resist from the surface of the substrate using a laser.

8. (Currently Withdrawn) The method according to claim 7 wherein said laser comprises a laser associated with an automolding system.

9. (Currently Withdrawn) The method according to claim 7 wherein said laser includes one of an Nd:YAG laser and an excimer laser.

10. (Currently Withdrawn) The method according to claim 7 wherein said substrate comprises a ball-grid-array substrate.

11. (Currently Withdrawn) The method according to claim 7 further comprising a vision system for detecting resist.

12. (Currently Withdrawn) (Previously Amended) The method according to claim 11 wherein said vision system comprises:  
providing a laser scanning system; and  
detecting changes in a pattern of the substrate.

13. (Currently Amended) A method of fabricating a semiconductor device in an automolding system comprising:  
providing an automolding system having a laser for etching resist from the surface of a substrate;  
providing a substrate having a surface;  
forming resist on at least a portion of the surface;  
laser etching the resist from at least a portion of the surface of the substrate; and  
encapsulating the substrate.

14. (Currently Cancelled)

15. (Original) The method according to claim 13 wherein said laser comprises one of an Nd:YAG laser and an excimer laser.

16. (Original) The method according to claim 13 wherein said substrate comprises a ball-grid-array substrate.

17. (Original) The method according to claim 13 further comprising a vision system for detecting resist.

18. (Previously Amended) The method according to claim 17 wherein said vision system comprises:  
providing a laser scanning system; and  
detecting changes in a pattern of the substrate.

19. (Currently Withdrawn) (Amended) A method of enhancing the adhesion of a compound to a surface of a substrate comprising:  
providing said substrate having said surface; and  
roughening the surface of the substrate.

20. (Currently Withdrawn) (Previously Amended) The method according to claim 19 wherein said roughening comprises removing contamination and foreign particles from said surface of the substrate.

21. (Currently Withdrawn) An automolding system comprising:  
providing a substrate having a surface;  
preheating the substrate;  
forming a resist layer;  
baking the substrate; and  
removing contaminants from the substrate using a laser.

22. (Currently Withdrawn) The automolding system of claim 21 wherein said laser comprises one of an Nd:YAG laser and an excimer laser.

23. (Currently Withdrawn) The automolding system of claim 21 further comprising:  
placing the substrate in a mold; and  
encapsulating the substrate.